L Number	Hits	Search Text	DB	Time stamp
1	31	(chip die) WITH edge WITH (concave NEAR shape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 14:45
2	200	(chip die) and (edge WITH (concave NEAR shape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 14:52
3	71	((chip die) and (edge WITH (concave NEAR shape))) and recess$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 14:53
4	901	(edge NEAR5 (concave NEAR shape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 14:59
5	232	((edge NEAR5 (concave NEAR shape))) and recess$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 14:53
6	41	(((edge NEAR5 (concave NEAR shape))) and recess$2) and (chip die wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 14:58
7	1276	array$3 NEAR waveguide NEAR grating$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 14:57
8	1	((edge NEAR5 (concave NEAR shape))) and (array$3 NEAR waveguide NEAR grating$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:00
9	0	20020113242.URPN.	USPAT	2003/03/13 14:58
10	368	(array$3 NEAR waveguide NEAR grating$1) and (chip die wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:00
11	1	((array$3 NEAR waveguide NEAR grating$1) and (chip die wafer)) and (edge NEAR5 (concave NEAR shape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 14:59
12	1	((array$3 NEAR waveguide NEAR grating$1) and (chip die wafer)) and (concave NEAR shape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 14:59
13	18048	concave NEAR shape	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:00

14	2775	(concave NEAR shape) and (chip die wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:56
15	1	((concave NEAR shape) and (chip die wafer)) and (array$3 NEAR waveguide NEAR grating$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:17
16	2304	(concave NEAR shape) and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:02
17	757	((concave NEAR shape) and (chip die)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:20
18	82	(((concave NEAR shape) and (chip die)) and substrate) and contour	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:03
19	1484	((concave NEAR shape) and (chip die wafer)) and (dic$3 cut$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:57
20	1063	(((concave NEAR shape) and (chip die wafer)) and (dic$3 cut$4)) and edge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:58
21	632	((((concave NEAR shape) and (chip die wafer)) and (dic$3 cut$4)) and edge) and (recess$2 groove$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:58
22	77	(((((concave NEAR shape) and (chip die wafer)) and (dic$3 cut$4)) and edge) and (recess$2 groove$1)) and (substrate NEAR material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:59
23	5	5327517.URPN.	USPAT	2003/03/13 15:50
24	7	("4373778" | "4647147" | "4729618" | "4976506" | "5015059" | "5054870" | "5076654").PN.	USPAT	2003/03/13 15:52
25	68221	(concave hollow$2 curv$3) NEAR shape	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:26
26	361381	"26" and (chip die wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:32
27	9861	((concave hollow$2 curv$3) NEAR shape) and (chip die wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:57

28	5283	(((concave hollow$2 curv$3) NEAR shape) and (chip die wafer)) and (dic$3 cut$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:27
29	4933	((((concave hollow$2 curv$3) NEAR shape) and (chip die wafer)) and (dic$3 cut$4)) and (edge end)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:37
30	2651	(((((concave hollow$2 curv$3) NEAR shape) and (chip die wafer)) and (dic$3 cut$4)) and (edge end)) and (recess$2 groove$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:58
31	177	((((((concave hollow$2 curv$3) NEAR shape) and (chip die wafer)) and (dic$3 cut$4)) and (edge end)) and (recess$2 groove$1)) and (substrate NEAR material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 15:59
32	1453	(chip$1 die$1 wafer$1) WITH ((concave hollow$2 curv$3) NEAR shape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:27
33	599	((chip$1 die$1 wafer$1) WITH ((concave hollow$2 curv$3) NEAR shape)) and (dic$3 cut$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:32
34	30	(((chip$1 die$1 wafer$1) WITH ((concave hollow$2 curv$3) NEAR shape)) and (dic$3 cut$4)) and ultrasonic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:32
35	1453	ultrasonic NEAR machin$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:32
36	346	(ultrasonic NEAR machin$3) and (chip die wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:32
37	212	((ultrasonic NEAR machin$3) and (chip die wafer)) and (dic$3 cut$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:33
38	8	(((ultrasonic NEAR machin$3) and (chip die wafer)) and (dic$3 cut$4)) and ((concave hollow$2 curv$3) NEAR shape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:37
39	9181	(semiconductor NEAR (chip$1 wafer$1)) WITH (dic$3 cut$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:37
40	137	((semiconductor NEAR (chip$1 wafer$1)) WITH (dic$3 cut$4)) and ((concave hollow$2 curv$3) NEAR shape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:54

42	1	((((semiconductor NEAR (chip$1 wafer$1)) WITH (dic$3 cut$4)) and ((concave hollow$2 curv$3) NEAR shape)) and (edge end)) and non-rectangular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:54
41	127	(((semiconductor NEAR (chip$1 wafer$1)) WITH (dic$3 cut$4)) and ((concave hollow$2 curv$3) NEAR shape)) and (edge end)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:39
43	3572	((semiconductor NEAR (chip$1 wafer$1)) WITH (dic$3 cut$4)) and (arrang$5 lay-out)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:54
44	4211	((semiconductor NEAR (chip$1 wafer$1)) WITH (dic$3 cut$4)) and (arrang$5 lay-out configur$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:54
46	1	((((semiconductor NEAR (chip$1 wafer$1)) WITH (dic$3 cut$4)) and (arrang$5 lay-out configur$5)) and ((concave hollow$2 curv$3) NEAR shape)) and non-rectangular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:54
45	123	(((semiconductor NEAR (chip$1 wafer$1)) WITH (dic$3 cut$4)) and (arrang$5 lay-out configur$5)) and ((concave hollow$2 curv$3) NEAR shape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/13 16:54
47	3	("4932064" | "6075280" | "6326697").PN.	USPAT	2003/03/13 16:58
48	0	6528864.URPN.	USPAT	2003/03/13 16:58
49	0	6528864.URPN.	USPAT	2003/03/13 16:58